

## General Description

SFGMOS<sup>®</sup> MOSFET is based on Oriental Semiconductor's unique device design to achieve low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. The high  $V_{th}$  series is specially optimized for high systems with gate driving voltage greater than 10V.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Fast switching and soft recovery



## Applications

- Switched mode power supply
- Motor driver
- Battery protection
- DC-DC convertor
- Solar inverter
- UPS and energy inverter

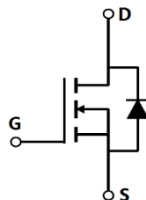
## Key Performance Parameters

| Parameter                      | Value | Unit      |
|--------------------------------|-------|-----------|
| $V_{DS, min} @ T_{j(max)}$     | 80    | V         |
| $I_D, pulse$                   | 390   | A         |
| $R_{DS(ON), max} @ V_{GS}=10V$ | 4.5   | $m\Omega$ |
| $Q_g$                          | 101.6 | nC        |

## Marking Information

| Product Name | Package | Marking    |
|--------------|---------|------------|
| SFG130N08PF  | TO220   | SFG130N08P |

## Package & Pin information



**Absolute Maximum Ratings** at  $T_j=25^{\circ}\text{C}$  unless otherwise noted

| Parameter   | Symbol         | Value      | Unit               |
|---|----------------|------------|--------------------|
| Drain source voltage  | $V_{DS}$       | 80         | V                  |
| Gate source voltage   | $V_{GS}$       | $\pm 20$   | V                  |
| Continuous drain current <sup>1)</sup> , $T_C=25^{\circ}\text{C}$         | $I_D$          | 130        | A                  |
| Pulsed drain current <sup>2)</sup> , $T_C=25^{\circ}\text{C}$             | $I_{D, pulse}$ | 390        | A                  |
| Continuous diode forward current <sup>1)</sup> , $T_C=25^{\circ}\text{C}$ | $I_S$          | 130        | A                  |
| Diode pulsed current <sup>2)</sup> , $T_C=25^{\circ}\text{C}$             | $I_{S, pulse}$ | 390        | A                  |
| Power dissipation <sup>3)</sup> , $T_C=25^{\circ}\text{C}$                | $P_D$          | 192        | W                  |
| Single pulsed avalanche energy <sup>5)</sup>                              | $E_{AS}$       | 400        | mJ                 |
| Operation and storage temperature   | $T_{stg}, T_j$ | -55 to 150 | $^{\circ}\text{C}$ |

**Thermal Characteristics**

| Parameter  | Symbol          | Value | Unit                 |
|--|-----------------|-------|----------------------|
| Thermal resistance, junction-case                  | $R_{\theta JC}$ | 0.65  | $^{\circ}\text{C/W}$ |
| Thermal resistance, junction-ambient <sup>4)</sup> | $R_{\theta JA}$ | 62    | $^{\circ}\text{C/W}$ |

**Electrical Characteristics** at  $T_j=25^{\circ}\text{C}$  unless otherwise specified

| Parameter                        | Symbol       | Min. | Typ. | Max. | Unit             | Test condition                            |
|----------------------------------|--------------|------|------|------|------------------|---|
| Drain-source breakdown voltage   | $BV_{DSS}$   | 80   |      |      | V                | $V_{GS}=0\text{ V}, I_D=250\ \mu\text{A}$ |
| Gate threshold voltage           | $V_{GS(th)}$ | 2.0  |      | 4.0  | V                | $V_{DS}=V_{GS}, I_D=250\ \mu\text{A}$     |
| Drain-source on-state resistance | $R_{DS(ON)}$ |      | 3.8  | 4.5  | $\text{m}\Omega$ | $V_{GS}=10\text{ V}, I_D=20\text{ A}$     |
| Gate-source leakage current      | $I_{GSS}$    |      |      | 100  | nA               | $V_{GS}=20\text{ V}$                      |
|                                  |              |      |      | -100 |                  | $V_{GS}=-20\text{ V}$                     |
| Drain-source leakage current     | $I_{DSS}$    |      |      | 1    | $\mu\text{A}$    | $V_{DS}=80\text{ V}, V_{GS}=0\text{ V}$   |

### Dynamic Characteristics

| Parameter                    | Symbol       | Min. | Typ. | Max. | Unit | Test condition   |
|------------------------------|--------------|------|------|------|------|--|
| Input capacitance            | $C_{iss}$    |      | 8681 |      | pF   | $V_{GS}=0\text{ V}$ ,<br>$V_{DS}=50\text{ V}$ ,<br>$f=1\text{ MHz}$                          |
| Output capacitance           | $C_{oss}$    |      | 6484 |      | pF   |  |
| Reverse transfer capacitance | $C_{rss}$    |      | 8.55 |      | pF   |  |
| Turn-on delay time           | $t_{d(on)}$  |      | 28.2 |      | ns   | $V_{GS}=10\text{ V}$ ,<br>$V_{DS}=50\text{ V}$ ,<br>$R_G=2.2\ \Omega$ ,<br>$I_D=22\text{ A}$ |
| Rise time                    | $t_r$        |      | 7.5  |      | ns   |  |
| Turn-off delay time          | $t_{d(off)}$ |      | 81.9 |      | ns   |  |
| Fall time                    | $t_f$        |      | 20.1 |      | ns   |  |

### Gate Charge Characteristics

| Parameter            | Symbol        | Min. | Typ.  | Max. | Unit | Test condition  |
|----------------------|---------------|------|-------|------|------|---|
| Total gate charge    | $Q_g$         |      | 101.6 |      | nC   | $V_{GS}=10\text{ V}$ ,<br>$V_{DS}=50\text{ V}$ ,<br>$I_D=22\text{ A}$ |
| Gate-source charge   | $Q_{gs}$      |      | 20.6  |      | nC   |   |
| Gate-drain charge    | $Q_{gd}$      |      | 28.7  |      | nC   |   |
| Gate plateau voltage | $V_{plateau}$ |      | 4.2   |      | V    |   |

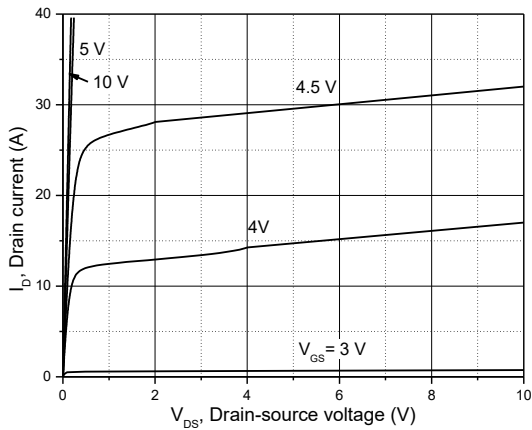
### Body Diode Characteristics

| Parameter                     | Symbol    | Min. | Typ.  | Max. | Unit | Test condition   |
|-------------------------------|-----------|------|-------|------|------|--|
| Diode forward voltage         | $V_{SD}$  |      |       | 1.3  | V    | $I_S=20\text{ A}$ ,<br>$V_{GS}=0\text{ V}$                                     |
| Reverse recovery time         | $t_{rr}$  |      | 82.1  |      | ns   | $V_R=50\text{ V}$ ,<br>$I_S=10\text{ A}$ ,<br>$di/dt=100\text{ A}/\mu\text{s}$ |
| Reverse recovery charge       | $Q_{rr}$  |      | 248.4 |      | nC   |  |
| Peak reverse recovery current | $I_{rrm}$ |      | 4.9   |      | A    |  |

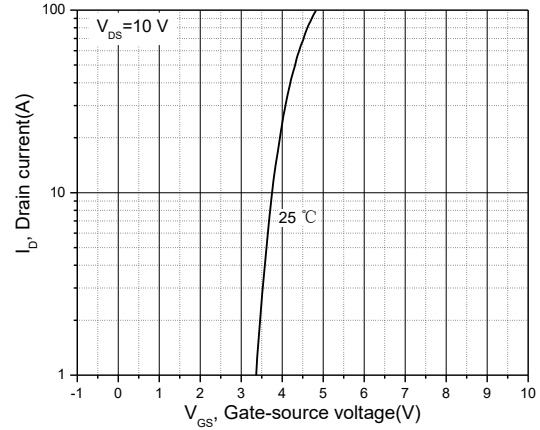
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25\text{ }^\circ\text{C}$ .
- 5)  $V_{DD}=50\text{ V}$ ,  $V_{GS}=10\text{ V}$ ,  $L=0.3\text{ mH}$ , starting  $T_j=25\text{ }^\circ\text{C}$ .

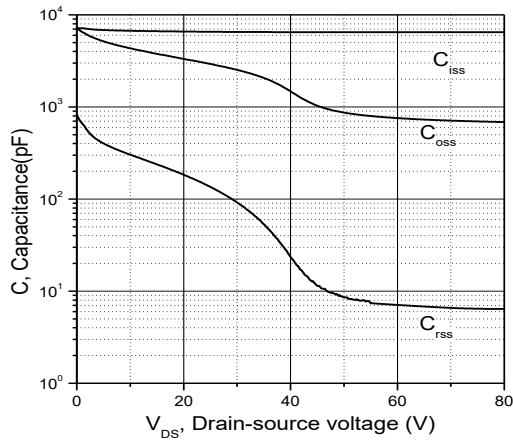
**Electrical Characteristics Diagrams**



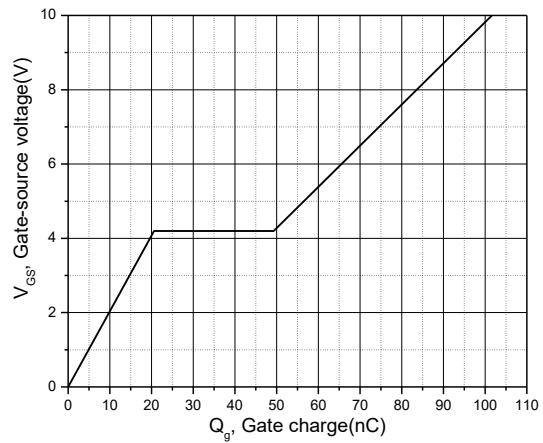
**Figure 1. Typ. output characteristics**



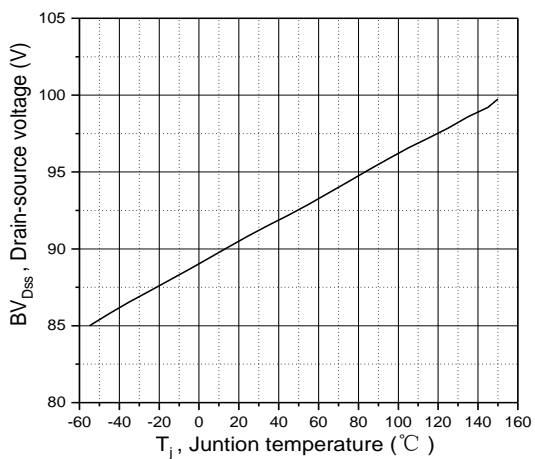
**Figure 2. Typ. transfer characteristics**



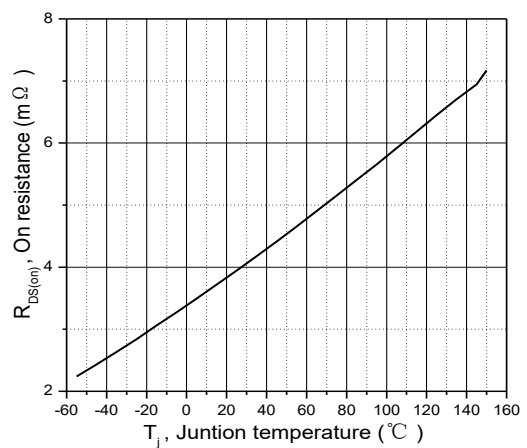
**Figure 3. Typ. capacitances**



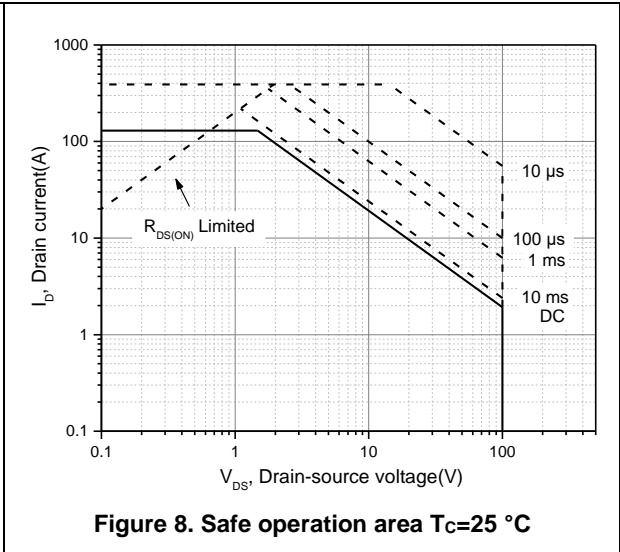
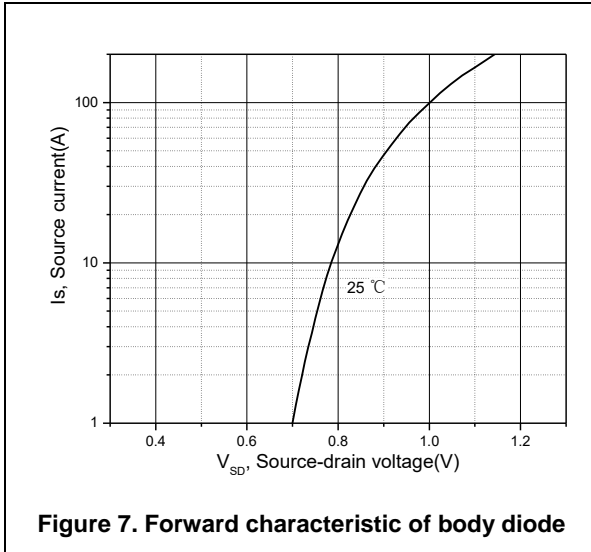
**Figure 4. Typ. gate charge**



**Figure 5. Drain-source breakdown voltage**



**Figure 6. Drain-source on-state resistance**



**Test circuits and waveforms**



**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

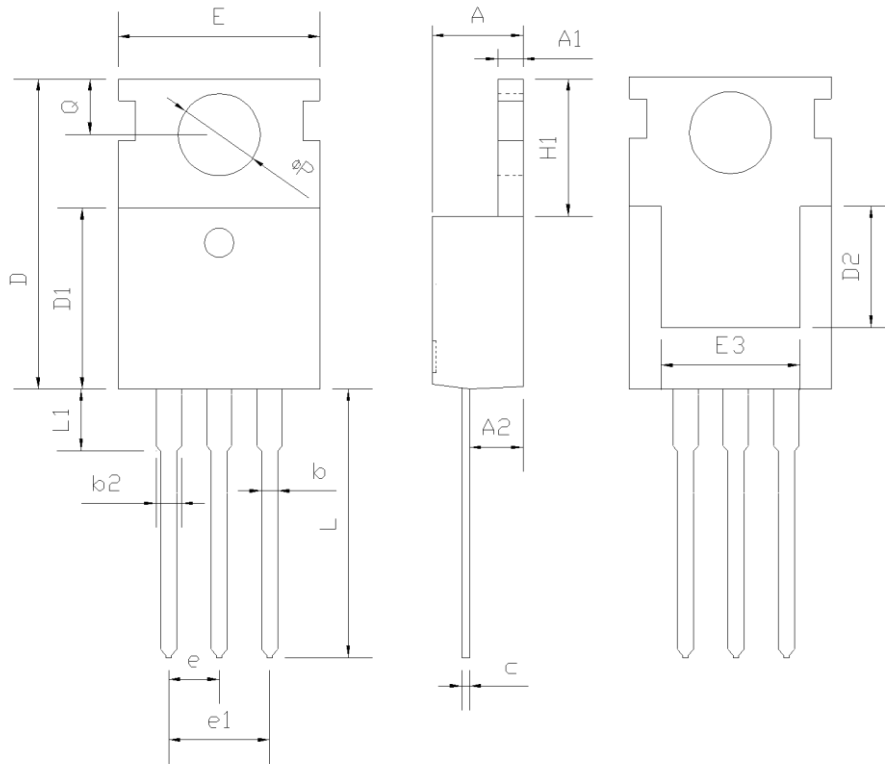


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

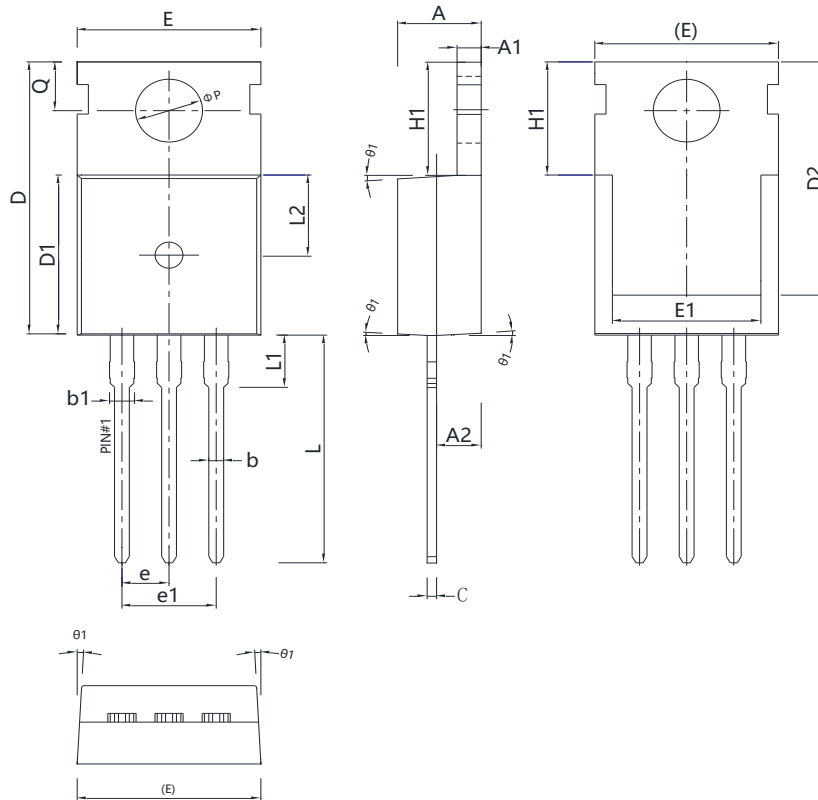
**Package Information**



| Symbol | mm       |       |       |
|--------|----------|-------|-------|
|        | Min      | Nom   | Max   |
| A      | 4.37     | 4.57  | 4.77  |
| A1     | 1.25     | 1.30  | 1.45  |
| A2     | 2.20     | 2.40  | 2.60  |
| b      | 0.70     | 0.80  | 0.95  |
| b2     | 1.17     | 1.27  | 1.47  |
| c      | 0.40     | 0.50  | 0.65  |
| D      | 15.10    | 15.60 | 16.10 |
| D1     | 8.80     | 9.10  | 9.40  |
| D2     | 5.50     | -     | -     |
| E      | 9.70     | 10.00 | 10.30 |
| E3     | 7.00     | -     | -     |
| e      | 2.54 BSC |       |       |
| e1     | 5.08 BSC |       |       |
| H1     | 6.25     | 6.50  | 6.85  |
| L      | 12.75    | 13.50 | 13.80 |
| L1     | -        | 3.10  | 3.40  |
| ΦP     | 3.40     | 3.60  | 3.80  |
| Q      | 2.60     | 2.80  | 3.00  |

Version 1: TO220-C package outline dimension

**Package Information**



| Symbol | mm       |       |       |
|--------|----------|-------|-------|
|        | Min      | Nom   | Max   |
| A      | 4.40     | 4.50  | 4.60  |
| A1     | 1.27     | 1.30  | 1.33  |
| A2     | 2.30     | 2.40  | 2.50  |
| b      | 0.70     | -     | 0.90  |
| b1     | 1.27     | -     | 1.40  |
| c      | 0.45     | 0.50  | 0.60  |
| D      | 15.30    | 15.70 | 16.10 |
| D1     | 9.10     | 9.20  | 9.30  |
| D2     | 13.10    | -     | 13.70 |
| E      | 9.70     | 9.90  | 10.20 |
| E1     | 7.80     | 8.00  | 8.20  |
| e      | 2.54 BSC |       |       |
| e1     | 5.08 BSC |       |       |
| H1     | 6.30     | 6.50  | 6.70  |
| L      | 12.78    | 13.08 | 13.38 |
| L1     | -        | -     | 3.50  |
| L2     | 4.60 REF |       |       |
| ΦP     | 3.55     | 3.60  | 3.65  |
| Q      | 2.73     | -     | 2.87  |
| θ1     | 1°       | 3°    | 5°    |

Version 2: TO220-J package outline dimension



### Ordering Information

| Package Type | Units/ Tube | Tubes / Inner Box | Units/ Inner Box | Inner Boxes/ Carton Box | Units/ Carton Box |
|--------------|-------------|-------------------|------------------|-------------------------|-------------------|
| TO220-C      | 50          | 20                | 1000             | 6                       | 6000              |
| TO220-J      | 50          | 20                | 1000             | 5                       | 5000              |

### Product Information

| Product     | Package | Pb Free | RoHS | Halogen Free |
|-------------|---------|---------|------|--------------|
| SFG130N08PF | TO220   | yes     | yes  | yes          |

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